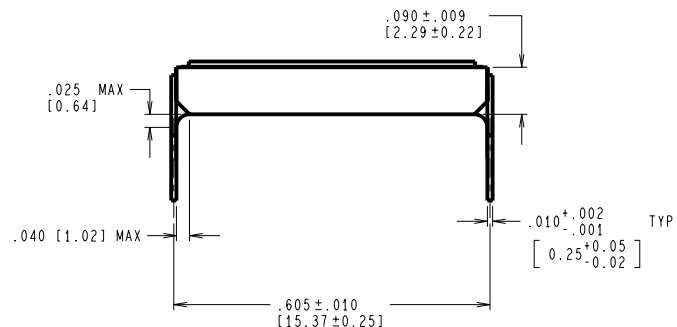
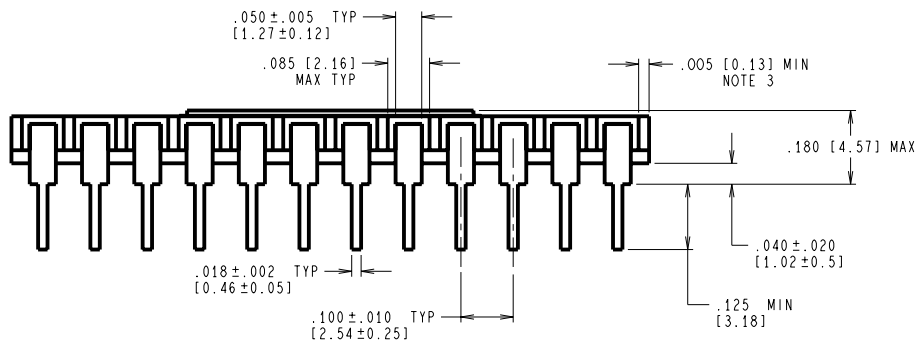
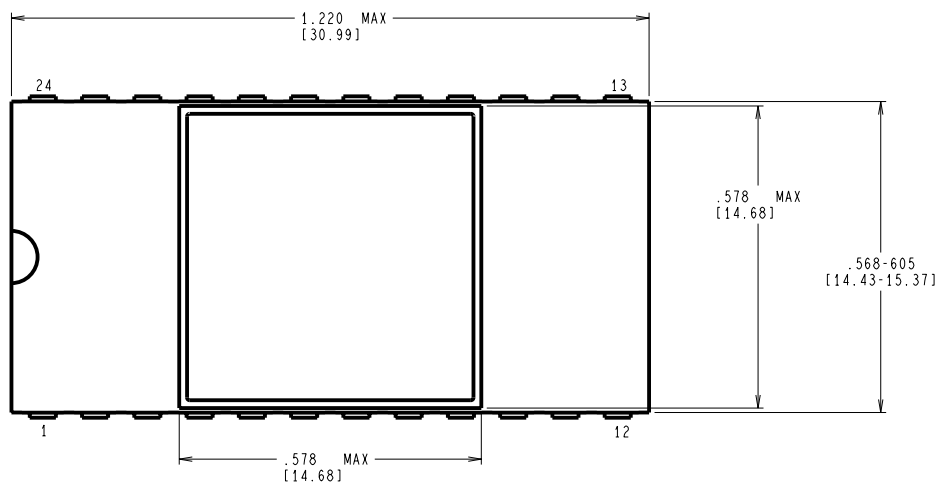


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE AND REDRAW PER NEW STANDARD.	10242	02/16/94	DEG/TP
J	.085 MAX WAS .080 ± .008; .568-.605 WAS .595 ± .006.	10473	07/01/94	DEG/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- REFERENCE JEDEC REGISTRATION MS-015, VARIATION CB, DATED 7/90.

MIL/AERO
CONFIGURATION CONTROL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	<i>Dwayne Grady</i>	02/16/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DTG. CHK.			DIP, SIDEBRAZED CERAMIC, 24 LEAD		
ENGR. CHK.					
APPROVAL					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-D24C	J
DO NOT SCALE DRAWING				SHEET 1 of 1	

INP
SEAL R
LID
LID RAD
LEADCO
BODY LE
BODY WI

* THIS PART #
IF THE LEAD
IF THE LEAD
IF THE LEAD